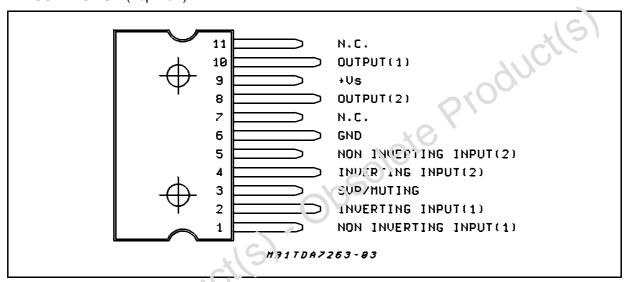
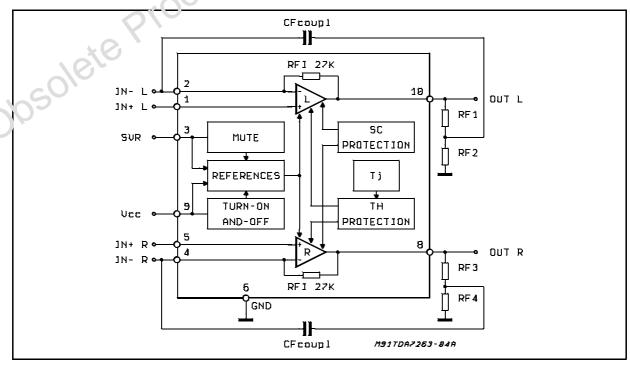
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vs	Supply Voltage without Load	35	V
lo	Output Peak Current (repetitive f >20Hz)	2	Α
P _{tot}	Total Power Dissipation (T _{case} = 70°C)	25	W
T _{op}	Operating Temperature Range	0 to 70	°C
$T_{stg,Tj}$	Storage & Junction Temperature	-40 to 150	°C

PIN CONNECTION (Top view)



BLOCK DIAGRAM



THERMAL DATA

Symbol	Parameter	Value	Unit
R _{th j-case}	Thermal resistance junction to case Max	3	°C/W

ELECTRICAL CHARACTERISTICS (Refer to the stereo test and application circuit, $V_S = 28V$; $R_L = 8_{\Omega}$; $G_v = 30dB$; f = 1KHz; $T_{amb} = 25^{\circ}C$ unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Vs	Supply Voltage		10		30	V
Vo	Quiescent Output Voltage			13.5		V
Ιq	Total Quiescent Current			70	95	mA
Po	Output Power (RMS)	d = 10% Tamb = 85°C d = 1%	10	12 9.5	. 10	W L VV
d	Total Harmonic Distortion	P _O = 1W, f = 1kHz f = 100Hz to 10KHz; P _O = 0.1 to 8W		0.02	9.2 0.5	%
СТ	Cross Talk	$R_S = 10K\Omega$; $f = 1KHz$		70)	dB
		$R_S = 10K\Omega$; $f = 10KHz$	35	6υ		dB
Rı	Input Resistance		150	200		ΚΩ
f∟	Low Frequency Roll-off (-3dB)	0		40		Hz
f _H	High Frequency Roll-off (-3dB)			80		KHz
en Total Input Noise Voltage		A Curve; Rs = 10 K Ω		1.5		mV
		f = 22Hz to 22KHz; Rs = 10KΩ		3	10	μV
SVR	Supply Voltage Rejection (each channel)	n $R_S = 10V_{.52}$, $t = 100Hz$; $Vr = 0.5V$		60		dB
Tj	Thermal Shutdown Junction Temperature			145		°C
MUTE FUNCTION						
VT_{MUTE}	Mute Threshold		1	1.6		V
VT_{PLAY}	Play Threshold			4.5		V
ATT_{AM}	Mute Attenuation		70	100		dB
I _{qMUTE}	Quiescen Current @ Mute			7	10	mA

TYPICAL CLARACTERISTICS (referred to the typical Application Circuit, $V_S = 28V$, $R_L = 8\Omega$, unless otherwise specified)

Figure 1: Output Power vs. Supply Voltage

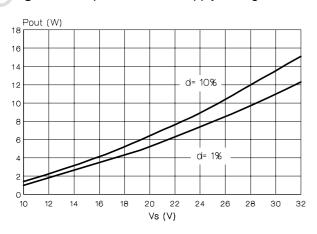
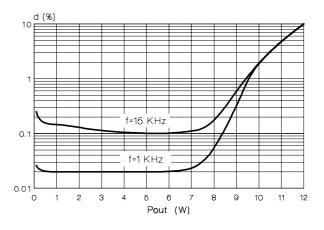


Figure 2: Distortion vs. Output Power



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Figure 3: Quiescent Current vs. Supply Voltage

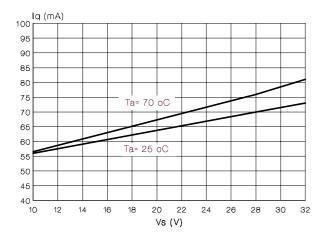


Figure 4: Supply Voltage Rejection vs. Frequency

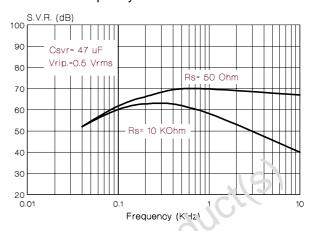


Figure 5: Crosstalk vs. Frequency

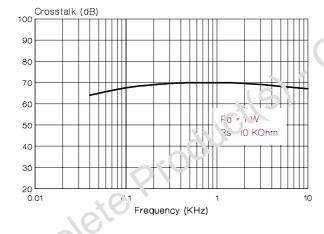


Figure 6: Output Attenuation & Quiescent Coment vs. Vpin3

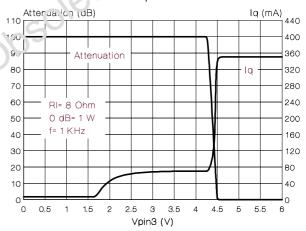


Figure 7: Total Power Dissipation vs. Output Power

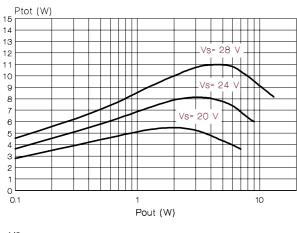
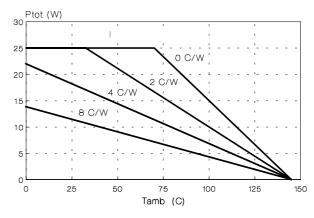


Figure 8: Maximum allowable Power dissipation vs. Ambient Temperature



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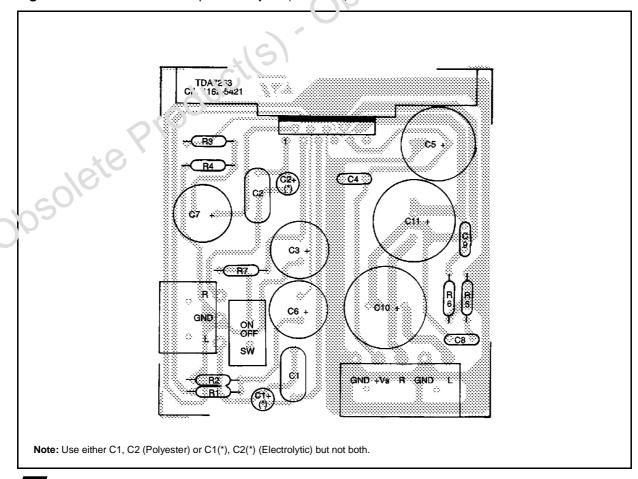
APPLICATION SUGGESTION

The recommended values of the components are those shown on the typical application circuit. Different values can be used; the following table can help the designer.

Component Recomm. Value		Purpose	Larger Than	Smaller Than		
R1 and R3	1.5KΩ	Close loop gain setting (*)	Increase of gain	Decrease of gain		
R2 and R4	47Ω	Close loop gain setting (*)	Decrease of gain	Increase of gain		
R5 and R6	4.7Ω	Frequency stability	Danger of oscillations			
C1 and C2	100nF	Input DC decoupling	Higher SVR	Higher low frequency cutoff		
C3	47μF	- Ripple Rejection - Mute time constant	Increase of the Switch-on time	- Degradation of SVR - Worse turn-off pop by muting		
C4	100nF	Supply Voltage Bypass		Danger of oscillations		
C5	1000μF	Supply Voltage Bypass		161		
C6 and C7	47μF	Feedback input DC decoupling	Increase of the Switch-on time	Danger of Switch-un time		
C8 and C9	0.1μF	Frequency stability		Danger of cacillations		
C10 and C11	1000μF	Output DC decoupling		'H ghor iow-frequency cut-off		

^(*) Closed loop gain must be higher than 26dB

Figure 9: P.C. Board and Component Layout (1:1 scak)



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BUILT-IN PROTECTION SYSTEMS

THERMAL SHUT-DOWN

The presence of a thermal limiting circuit offers the following advantages:

- 1-an overload on the output (even if it is permanent), or an excessive ambient temperature can be easily withstood.
- 2-the heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no device damage in the case of excessive junction temperature; if for any Obsolete Product(s). reason the junction temperature increases up to 145°C, the thermal shutdown simply re-

duces the output power and therefore the power dissipation.

The maximum allowable power dissipation depends upon the thermal resistance junction-ambient. Figure 8 shows the dissipable power as a function of ambient temperature for different heatsink thermal resistance.

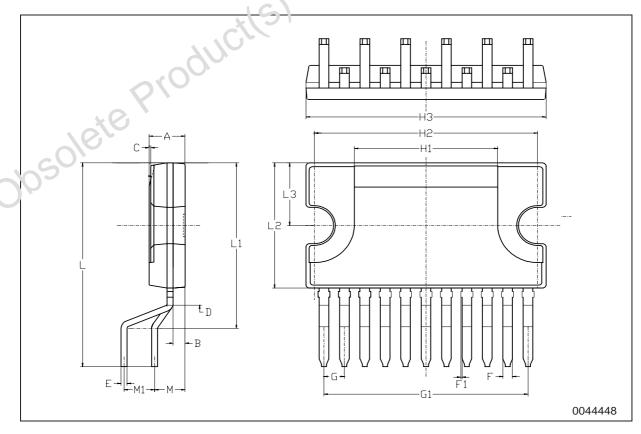
SHORT CIRCUIT (AC CONDITIONS)

The TDA7263 can withstand accidental short circuits across the speaker made by a wrong connection during normal play operation.

DIM.	mm			inch		
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			3.2			0.126
В			1.05			0.041
С		0.15			0.006	
D		1.5			0.059	
Е	0.49		0.55	0.019		0.002
F	0.77	0.8	0.88	0.030	0.031	0.035
F1			0.15			0.006
G	1.57	1.7	1.83	0.062	0.067	0.072
G1	16.87	17	17.13	0.664	0.669	0.674
H1		12			0.480	
H2		18.6			0.732	
НЗ	19.85			0.781		
L		17.9			0.700	
L1		14.55			0.580	
L2	10.7	11	11.2	0.421	0.433	0.441
L3		5.5			0.217	
М		2.54			0.100	
M1		2.54			0.100	

OUTLINE AND MECHANICAL DATA







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